

Our magnetism are designed to provide high quality, uniform coatings for your application

ADVANCED MAGNET SYSTEM FEATURES:

- Multiple magnetism designs to fit your application requirements
- Advanced magnetism designed using 3D finite element analysis software
- Carefully matched, hi-strength magnetism that are sorted in-house using a magnet gauss measurement tool
- Fully encapsulated magnetism and robust construction for many years of trouble-free operation
- Long-life, multi-roller system for sputter up, sputter down, or off-angle sputtering
- Magnetism uniformity adjustment can be done easily in the field
- Simple installation procedure with solutions for vertical installations

BENEFITS:

- Industry leading coating uniformity as good as +/- 1%
- Superior target utilization and reduced cross corner effects
- Higher deposition rates
- Lengthen campaign - increase uptime with better target utilization
- Sputter up or sputter down



Advanced Magnet Bars

NEW SYSTEM INSTALLATIONS:

- Most versatile rotary magnetism systems available
- Horizontal and vertical use
- Custom length magnet bar to ensure the perfect match for your application

UPGRADE OLD MAGNET BARS:

- Interchangeable with other major manufacturers
- Can adapt to any end block system
- Eliminate the need to replace magnet bars due to corroded magnetism
- Increase production yields by reducing process drift and increasing target utilization



SCI QRM high strength magnet assembly with 90% utilization on a 152mm diameter target.

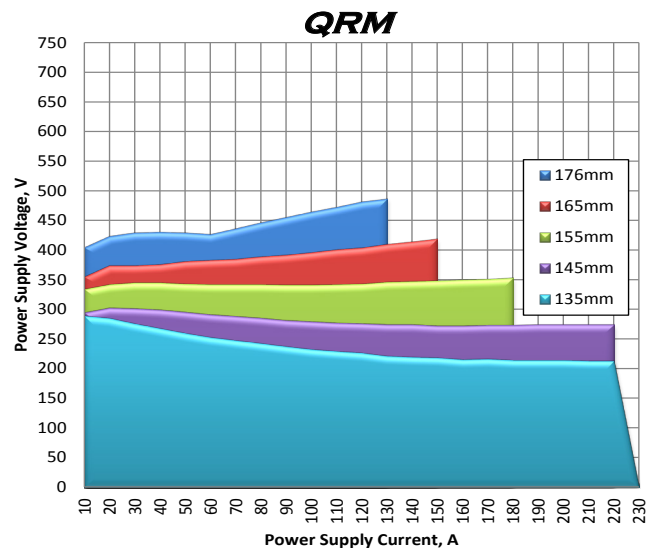
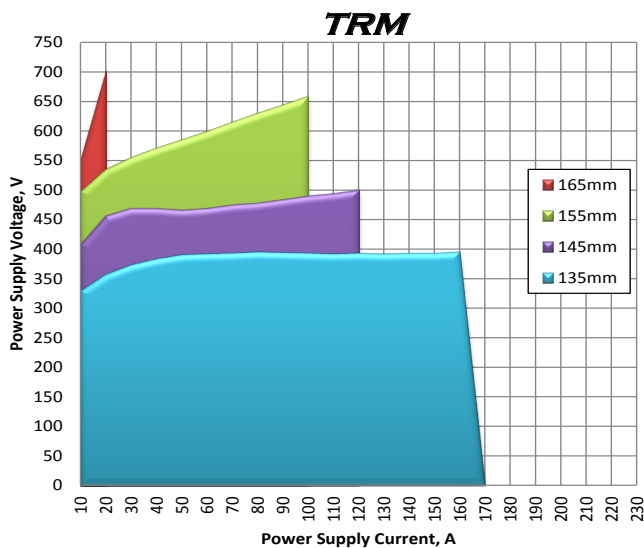
TRM-Bar™ Magnetics FEATURES AND BENEFITS

- Industry-proven design with thousands of bars currently in operation
- High rate reactive mode or metal mode sputtering of optical grade films
- Narrow deposition profile minimizes coating losses to waste shields
- Multiple turn-around designs for different application requirements
- The turn-arounds can be easily changed

QRM-Bar™ Magnetics FEATURES AND BENEFITS

- Stronger "patent pending" magnetics for low impedance sputtering of TCOs and other electrical grade films
- Lower impedance plasma enables higher power densities and higher achievable sputter rates for most materials.
- Increased sputtering efficiencies reduce power consumption and operating costs
- Increased process stability over the lifetime of the target material

650mm long aluminum target impedance comparison for 135mm to 175mm O.D.



Test Condition: 650mm long aluminum target tube, 60kW advanced energy AEPN power supply, 3mTorr of Argon in metal mode

Model	Utilization	Uniformity	Max Target O.D.
TRM	>70% (152mm)	+/- 2%	165mm
TRM - SCI Tapered Target	>80% (152mm)	+/- 2%	165mm
TRM - High Utilization	Up to 90%	+/- 2%	165mm
QRM	>85% (155mm) >75% (165mm)	+/- 1%	175mm
		+/- 1%	175mm